

IN THE SPECIFICATION

Please replace the paragraph beginning at page 1, line 4, with the following rewritten paragraph:

The present invention relates essentially to a ceramic substrate for the various apparatuses of use in the manufacture and inspection of semiconductor devices, such as the hot plate (ceramic heater), electrostatic chuck, wafer ~~prober~~ prober and so on.

Please replace the paragraph beginning at page 1, line 11, with the following rewritten paragraph:

As the apparatuses for use in the manufacture and inspection of semiconductor devices, inclusive of etching equipment and chemical vapor-phase propagation equipment, for instance, the heater, wafer ~~prober~~ prober, etc. each comprising a substrate of metal such as stainless steel or aluminum alloy have heretofore been employed.

Please replace the paragraph beginning at page 3, line 15, with the following rewritten paragraph:

Fig. 1 is a schematic longitudinal section view showing an electrostatic chuck as an example of application of the ceramic substrate or sintered aluminum nitride body according to the invention;

Fig. 2 is a sectional view taken along the line A-A of Fig. 1;

Fig. 3 is a sectional view taken along the line B-B of Fig. 1;

Fig. 4 is a schematic sectional view showing an example of the static electrode pattern of an electrostatic chuck;

Fig. 5 is a schematic section view showing another example of the static electrode pattern of an electrostatic chuck;

Fig. 6 is a schematic section view showing a wafer ~~prover~~ prober as an example of application of the ceramic substrate or sintered aluminum nitride body according to the invention;

Fig. 7 is a sectional view taken along the line A-A of Fig. 6;

Fig. 8 (a) ~ (d) are schematic section views showing a part of the manufacture process of an electrostatic chuck; and

Fig. 9 is a sectional view of a heater employing the ceramic substrate or sintered aluminum nitride body of the invention.

Please replace the paragraph beginning at page 8, line 2, with the following rewritten paragraph:

The ceramic substrate or sintered aluminum nitride body according to the present invention is a ceramic substrate for use in the apparatuses for the manufacture or inspection of semiconductor devices and, as specific apparatuses, there can be mentioned electrostatic chucks, wafer ~~provers~~ probers, hot plates and susceptors, among others.

Please replace the paragraph beginning at page 15, line 1, with the following rewritten paragraph:

When the ceramic substrate for semiconductor devices employing the ceramic substrate or sintered aluminum nitride body of the present invention is provided with a conductor on its surface as well as internally and the internal conductor is at least either a guard electrode or a ground electrode, the ceramic substrate may function as a wafer ~~prover~~ prober.

Please replace the paragraph beginning at page 15, line 8, with the following rewritten paragraph:

Fig. 6 is a schematic cross-section view showing a wafer ~~prover~~ prober 201 as an embodiment of the ceramic substrate or sintered aluminum nitride body of the present invention and Fig. 7 is a sectional view of the same wafer ~~prover~~ prober as taken along the line A-A of Fig. 6.

Please replace the paragraph beginning at page 15, line 13, with the following rewritten paragraph:

In this wafer ~~prover~~ prober 201, a plurality of grooves 47 circular in plan view and arranged in concentric relation are formed on the surface of the ceramic substrate 43 which is also circular in plan view, with a plurality of suction holes 48 for attracting a silicon wafer being strategically formed in said grooves 47, and a chuck top conductive layer 42 for electrical connection to electrodes of a silicon wafer is formed in a circular pattern on most of the surface of the ceramic substrate 43 inclusive of said grooves 47.

Please replace the paragraph beginning at page 16, line 11, with the following rewritten paragraph:

With the wafer ~~prover~~ prober constructed as above, a continuity test can be performed by placing a silicon wafer formed with an integrated circuit on the ~~prover~~ prober, pressing a probe card carrying tester pins against the wafer, and applying a voltage under heating and cooling.

Please replace the paragraph beginning at page 20, line 15, with the following rewritten paragraph:

Thus, the ceramic substrate and sintered aluminum nitride body according to the present invention can be applied to various apparatuses for use in the manufacture or inspection of semiconductor devices, such as the hot plate (ceramic heater), electrostatic chuck, wafer ~~prober~~ prober, and susceptor.

Please replace the sub-title at page 28, line 4, with the following rewritten sub-title:

Manufacture of a wafer ~~prober~~ prober 201 (Fig. 6)